

MiNaPAD 2024 – Conference overview



Wednesday June 19th

8h15	Welcome to MiNaPAD – Coffee & Soft drink sponsored by ASE		📍 Exhibition Hall
9h00	Opening 🧑‍🎓 Jean-Marc Yannou		📍 Auditorium
9h10	Keynote ▶ The Future of Semiconductor Package Manufacturing in Europe: Growing or Vanishing 🧑‍🎓 Steffen Kröhnert, President & Founder of ESPAT Consulting – SEMI Europe Manager, Germany		
	Session A ▶ AI Applications 📍 Auditorium	Session B ▶ Attachment materials 📍 Mont Blanc	
9h45	Detection and measurement of solder voids in X-ray of led assembly with YOLO v8 🧑‍🎓 Yasser Almehio, VALEO, France	The Application of Low Temperature Self-Assembly Sn Based Glue 🧑‍🎓 Glenn Lin, ASE group, Taiwan	
10h15	Solder paste development using AI 🧑‍🎓 Melanie Mathon, INVENTEC, France	New Bare Copper Compatible Die Attach Developments Improving Reliability and Thermal at Lower Cost 🧑‍🎓 Ruud De Wit, HENKEL, The Netherlands	
10h45	Exhibition Opening – Coffee break sponsored by STMicroelectronics		📍 Exhibition Hall
	Session C ▶ Interconnections 📍 Auditorium	Session D ▶ PCB Substrates 📍 Mont Blanc	
11h15	Integration of III-V GaN amplifiers of an antenna in package receiver in PCB-based embedding technology 🧑‍🎓 Tekfouy Lim, FRAUNHOFER IZM, Germany	Advanced IC substrates – Challenges in the manufacturing and supply chain 🧑‍🎓 Roland Steim, DYCONEX, Switzerland	
11h45	Alternative approach to Die-to-Wafer bonding utilizing atmospheric plasma cleaning 🧑‍🎓 Daniel Pascual, ONTOS - USA	High Density Organic Substrates for Chiplet and High Frequency Application 🧑‍🎓 Lars Bottcher, FRAUNHOFER IZM, Germany	
12h15	Clips bonding using re-metallization techniques 🧑‍🎓 Wilfrid Aklamavo, SERMA Microelectronics, France		
12h45	Lunch sponsored by Teledyne e2V		📍 Exhibition Hall
	Session E ▶ Process Optimization 1 📍 Auditorium	Session F ▶ Reliability 1 📍 Mont Blanc	
13h45	An innovative deposition technology for conductive & dielectric materials; Multimaterials, Multilayers, Contactless High-Resolution High-Speed Deposition 🧑‍🎓 Stéphane Étienne, I-O-TECH, Israel	Robustness and environmental impact of under bump metallization for wafer level balling 🧑‍🎓 Arnaud Garnier, CEA LETI, France	
14h15	SWEET (Side Wall Exquisite Enveloping Technology) to protect WLSCP 🧑‍🎓 Shih Chieh Tang, ASE group	SACN doped Mn solder balls oxidation study for BGA's reliability performance 🧑‍🎓 Stelliane Grolier Lee, STMicroelectronics, France	
14h45	Post plasma dicing clean in Batch spray equipment with sulfuric ozone mixtures 🧑‍🎓 Moritz Mittermayr, SICCONNEX, Austria	Experimental study of interfacial adhesion of passivation/resin with shear test: first learnings 🧑‍🎓 Marie Dugor Dentone, STMicroelectronics, France	
15h15	Exhibition – Coffee break sponsored by Accelonix		📍 Exhibition Hall
	Session G ▶ Dicing/Picking 📍 Auditorium	Session H ▶ Flip Chip Process 📍 Mont Blanc	
15h45	Plasma Singulation of Single Power Diodes Bonded by Intermetallic Eutectic Technique 🧑‍🎓 Sabrina Roza-Ortiz, PLASMATHERM, USA	Development of a dipping process for silver sintered flip chip interconnexion 🧑‍🎓 Céline Feautrier, CEA LETI, France	
16h15	Latest approaches of dicing and grinding for semiconductor device manufacturing 🧑‍🎓 Benjamin Bernard, DISCO, Germany	Flux less soldering in activated hydrogen atmosphere 🧑‍🎓 Jeff Blair, SIKAMA, USA	
16h45	Industrial Approach for Plasma Dicing: Advances and Challenges 🧑‍🎓 Lucile Broussous, STMicroelectronics, France	Displacement mechanisms of polymer adhesives used in the flip chip interconnected structures 🧑‍🎓 Nacer Aitmani, CEA LETI, France	
17h15	Precision plasma dicing of wafers 🧑‍🎓 Leslie Lea, PLASMATHERM, USA	Innovative interconnect material for semiconductor assembly and advanced packaging 🧑‍🎓 Sze Pei Lim, INDIUM, United Kingdom	
17h45	Exhibition		📍 Exhibition Hall
18h30	Social Event: Departure		

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8h30	Opening exhibition and conferences		
9h10	Keynote ▶ What are our common Challenges for Future? 🧑‍🎓 Thomas Romont, Senior PCB Expert, IFTEC, France		
	Session J ▶ Power Management 📍 Auditorium	Session K ▶ Characterization 📍 Mont Blanc	
9h45	Understanding Criticality of Thermal Performance in Thermal Interface Material for Automotive Applications 🧑‍🎓 Nicolas Riem, HENKEL, TheNetherlands	Dual blocks QFN warpage characterization 🧑‍🎓 Federico Leone, STMicroelectronics, Italy	
10h15	Packaging and reliability challenges for Innovative Automotive Grade current sensors 🧑‍🎓 Alastair Attard, UTAC, Switzerland	Die bending methodology to explore Deep Trench Isolation crack initiation risk in Backside Imager Sensors 🧑‍🎓 Caroline Moutin, STMicroelectronics, France	
10h45	Exhibition – Coffee break sponsored by Caplinq		📍 Exhibition Hall
	Session L ▶ Process Optimization 2 📍 Auditorium	Session M ▶ Sustainability 📍 Mont Blanc	
11h15	In Situ characterization of plasma species for process optimization and improvement 🧑‍🎓 Djamilia Chou, STMicroelectronics, France	Fabrication of low density 3D PCB using piezo-ink jet and 6 axis robots 🧑‍🎓 Davide Benneventi, INPG, France	
11h45	Direct silicon wafer bonding outside cleanroom conditions 🧑‍🎓 Chrysoula Nikoleta Manolaki, DTU Electro, Denmark	High Precision Capillary Printing HPCAP and its sustainable value in electronics 🧑‍🎓 Julien Vitiello, HUMMINK, France	
12h15	Two steps collective bonding, from dicing-tape to device over 10000 UPH 🧑‍🎓 Aurélien Griffart, SET, France	Sustainable and circular PCB using biobased/biodegradable substrates and metals bioleaching 🧑‍🎓 Vincent Grennerat, INPG CROMA, France	
12h45	Exhibition – Lunch sponsored by Kyocera		📍 Exhibition Hall
	Session N ▶ Molding process 📍 Auditorium	Session O ▶ Reliability 2 📍 Mont Blanc	
13h45	Environment-friendly Epoxy Molding Compounds for Semiconductors and Automotive 🧑‍🎓 Takahiro Watanabe, Sumitomo Bakelite Co. Ltd, Japan	Enhanced Board Level Reliability Method for High Performance Automotive BGA Packages 🧑‍🎓 Nohora Caicedo, STMicroelectronics, France	
14h15	Advanced Mold Design Solutions to Counteract Surface Discoloration in Flip Chip Encapsulation 🧑‍🎓 Roberto Dossi, ASE group, Taiwan	The Effects of Voids on Solder Joint Reliability in First Level Interconnect 🧑‍🎓 Sze Pei Lim, INDIUM, United Kingdom	
	Session P ▶ Interposer 2.5D TSV 3D 📍 Auditorium		
14h55	Design and verification of a 2.5 Heterogeneous Integration Platform 🧑‍🎓 Jeroen Schelkens & Dimitrios Tsiakos, IMEC, Belgium		
15h25	Unlocking the Trends and Challenges in Advanced 3D Heterogeneous Integration Manufacturing 🧑‍🎓 Rayane Mazari, YOLE Group, France		
15h50	Hermetically sealed glass interposer platform for photonics integrated circuits 🧑‍🎓 Kevin Kroehnert, FRAUNHOFER IZM, Germany		
16h15	Si Based integrated passive devices for Sub 6G SiP 🧑‍🎓 Mark Azzopardi, JCET group, Switzerland		
16h45	Closing MiNaPAD 2024 Conference 🧑‍🎓 Jean-Marc Yannou		📍 Auditorium